Comparing the Temperature-Levelling Capabilities of Solid-Solid Phase Transition Materials for Thin Device Thermal Control of Semiconductor Chips

S Farook1, S Kaliappan2,a)

1 Department of EEE, Mohan Babu University, Tirupati, Andhra Pradesh - 517102, India.

2 Division of Research and Development, Lovely Professional University, Jalandhar - Delhi G.T.Road, Phagwara, Punjab (India) – 144411.

Corresponding author: a)[srini.kal\_lpu@yahoo.com](mailto:srini.kal_lpu@yahoo.com)

**Abstract:** Solid-solid materials with phase changes, or PCMs, are being used in cooling to increase the robustness of smart gadgets, including tablets and phones. This method can be miniaturised and uses the unused energy of polycrystalline semiconductors (PCMs) to stabilise fluctuations in temperatures in electronic devices without the need for additional electrical power. Ambient thermophysical characteristics, its thickness, and the heat concentration of the radiation source all affect how well thermal control devices employing solid-solid PCMs balance temperature. These elements nevertheless make comparing PCM performance more difficult. Consequently, identifying an attribute of performance and elucidating the connection among those variables and the solid-solid PCMs' ability to level temperatures are essential for the growth of the material. We established an assessment index of PCMs appropriate for lightweight smart phones in this work. To determine the efficiency aspect, the temperature-levelling capabilities of nickel, titanium, and oxygen consumption, two common artificial solid-solid PCMs, were contrasted. Temperature models were employed to determine and compute the ideal PCM thicknesses for various heat densities produced by a heat source in order to maximise thermal levelling efficiency and economics.

**Keywords:** Temperature; Heat flow; Phase change materials; Thermal management; Levelling performance.

# Introduction

High computing rates have led to a rise in the temperature-generating concentration. concentration noun the act, process, or ability of concentrating; the process of becoming concentrated; or the state of being concentrated. A field or course of study on which one focuses, especially as a student in a college or university. The proportion of a substance as a whole. The amount of solute in a solution measured in suitable units (e.g., parts per million (ppm)) The matching game is Pelmanism [1]. Fans and cooling from water are examples of proactive thermal control approaches that are not compatible with all intelligent gadgets. Active thermal management equipment is thus necessary. To lessen shifts in temperature in semiconductors, temperature control via a material with a phase change (PCM) may be used. This passive heat-management technique depends on the unused heat generated by the PCM. Due to its ability to be miniaturised and the lack of extra power needed for heat control, the method has attracted a lot of interest. PCMs may be roughly divided into two types: solid-liquid and solid-solid. For the purpose of preventing liquid leakage during temperature control, solid-liquid PCMs like beeswax need to be contained. Additionally, wax has a very poor heat conductance (κ). Consequently, to increase the temperature responsiveness of solid-liquid PCMs, thermal conductor enhancers (TCEs) are added [2,3]. Solid-solid PCMs, on the other hand, don't need containers, making them better suited for gadget heat control. Additionally, a large category of solid-solid PCMs includes inorganic Since inorganic particles have a larger κ value than biological PCMs, it is possible to derive high-temperature responses from them without the need for TCEs. Thus, we concentrated on solid-solid These particles are part of our investigation. VO2 is a common PCM that is chemically solid. Specifically, W pumping may be used to regulate the near-ambient transition temperature (Tm = 68 °C) of VO2, a metal-insulator crossover substance, making it a potential irreversible PCM. This means that VO2 has a volume thermal conductivity (Lv) of around 270K. NiTi is a PCM with super flexibility and shape-memory properties that relies on the martensitic phase shift. Depending on the alloy's structure and its treatment with heat, the melting point of NiTi varies within an acceptable range of -20 to 100 degrees Celsius. While VO2's κ is multiple states times greater than Niti's, the latter has a lower Lv. Consequently, in order to compare the temperature-levelling capabilities of both of those PCMs, it is important to ascertain the link among their thermophysical characteristics and capabilities [4].

Lin claims that an amount of merit (FOM), which is an outcome of Lv as well as the low temperature phase's (κl) thermal efficiency, may be utilised for assessing the efficacy of PCMs. The field of view (FOM) is obtained by making the assumption that a high-power heat burst heats the outermost layer of a PCM with a limited depth. Notably, large-power heat bursts may be absorbed by a PCM with an elevated FOM. The paraffin VO2 as far as possible with phase changes at frequencies between 50 and 70 °C has been observed. Due to their large FOMs relative to other recognised ad Non-Oxford British English standard spelling of recognized. verb simple past tense and past participle of recognise Report Word PCMs, we examined and evaluated the temperature-levelling capabilities of VO2 with nickel titanium in our work. In an earlier work, we assumed constants for q and PCM thicknesses (w) and evaluated the impact of thermophysical characteristics, such as κ, specific heat (c), and Lv, the temperature-levelling capability of a PCM. The mounting form of the examined PCMs is not taken into account by these assessment techniques, despite the fact that these PCMs' thermophysical characteristics are usually used to forecast future temperature-levelling capabilities. The ideal form and thickness for a phase change material (PCM) vary based on the electronics device's geometry and heat flow. Infrared simulations are being used to assess the heat sink's ability to level temperatures using solid-liquid PCM. Even in this instance, nevertheless, it is unclear how the shape and flow of heat affect the efficiency of heat levelling. In the present study, we established an assessment metric for PCMs installed on a thin mobile device that utilised an off-chip architecture. We can assess how the dimensions of the PCM affect the ability to regulate temperatures by providing the gadget [5].

The ideal PCM width (wopt) was established, and oxygen consumption and NiTi's temperature-levelling capabilities were contrasted using a recently suggested performance measurement called maximal efficient energy capability. Initially, the thermal properties of a NiTi sheet and VO2-sintered bodies were investigated. The obtained thermophysical parameters were then used in a thermal simulation to determine Eeff. Tests using heaters and manufactured PCMs were carried out to validate the modelling findings.

# Optimal thickness of a solid–solid PCM

In order to assess the temperature-levelling capabilities of a solid-solid PCM installed on a narrow smartphone with an off-chip topology, we established a parameter for that matrix. The association between a computer chip's temperature (Te) and the phase change of a PCM is shown schematically in the first figure, along with a description of on-chip thermal regulation employing a PCM. The PCM was installed behind a heat sink or thermal spread and the power chip. Core computing units (CPUs), along with other electronic components, are equipped with configurable thermal management capabilities, including thermal restricting, which lowers the speed of processing and keeps the temperature below a certain level [11-15]. Because of its heat storage capacity, a PCM may keep a CPU at a temperature that is low, allowing the computer chip to operate at a high level of processing for an extended period of time. Heat is released into the environment via a heat sink or diffuser; with thin smart gadgets, their housing typically acts as the thermal distributor. The PCM reduces the amount of detail involved in employing several temperature-dissipating modules by connecting the circuitry of the component and heat splitter with the most minimal feasible thermal conductance [16-20].

# Sample preparation and analysis of thermophysical properties

## Preparation of a VO2-sintered body

We created a VO2-sintered organism and studied its thermophysical characteristics. A readily accessible 98.24% VO2 powdered with grains smaller than 170 μm was produced using plasma-spark smelting for 30 minutes in the absence of oxygen at 920 °C and 320 MPa. The flattened specimen was then annealed for 24 hours at 420 °C in the absence of oxygen to reduce the tension that had been created in the sintering procedure [21-27]. The average density in the sintering physique, measured through experimentation, was 4.36 g/cm3, or 91.1% of the value that is determined by using the molecular mass and a single cell capacity [6, 28-30].

## Preparation of NiTi alloy

A readily obtainable plate containing Nichols at 50.14 at% and w = 1 mm was treated with heat in order to create the NiTi test. A form of antioxidant was initially applied to the coated surface of 10 mm-diameter nickel titanium sheet fragments that had been cut from them. The resulting pieces then underwent heating for 30 minutes at 600 °C and were then quenched. Eventually, grinding was used to get rid of the protective coatings from the NiTi specimens' surface [31-37].

# Thermal simulation

## Simulation model

To compute wopt, a heating simulator was run employing a heat circuit architecture. Every node in the network in question was subjected to the approximated temperature capacity approach. To make certain that the Biot number was substantially less than one, an overall of twenty-one nodes were used. The simulated approach, which is a limited, unstable model with a PCM and heaters that simulates a computer chip, is shown in the third figure 1. In this type, one surface of the PCM is in contact with outside air, whereas the other has been attached to the heaters [38-40]. The previously heated heater's lowermost layer is adiabatic, and its lower node produces a constant q that, for a computer system like a CPU, ranges from 10–103 kW/m2. As a result, q was adjusted in our model calculations to vary between 20 and 120 kW/m2. The heater's thermophysical characteristics and simulation settings are shown in Table 2 below. To replicate the characteristics of the pottery heaters utilised for the confirmation test, we employed the thermophysical characteristics of aluminium for the computations carried out in this work (more information is given in Section 5). The simulations also made use of the PCM's observed thermophysical characteristics. The model included formulas and methods that were taken from our earlier research. The differential calculations were used to determine each node's temperature per second [7, 41-45]. The radiant heating energy and heating capacity were used to determine each node's temperature in temperatures other than To to Tm. On the other hand, the heat output and Lv—which were presumed to be constant values irrespective of temperature—were used to determine each node's temperature in a temperature range between To and Tm [8, 46-50].



**Figure 1**. Heat generation density based on thickness of the vessel

The findings of the test and simulation are shown in Figure 2. Ta was recorded at 20.2 ± 1.1 °C throughout the investigation [9]. Using identical circumstances, measurements were done multiple times. The recorded heat waveforms' relative standard deviations were below 3.4%, which suggests that the procedure has a high degree of reproducibility [10]. It seems that there is a strong correlation between simulation results and actual outcomes [11]. However, despite a good match between the model results and data from experiments, a notable discrepancy is seen with the completion of the phase transition, leading to the formation of a high-temperature PCM stage since the model assumes continuous thermophysical characteristics [12]. When an extreme-temperature PCM phase is created, the disparity between the simulation and the experiments increases since κ of the low-temperature phases is utilised in the model [13]. This research investigated the link between thermophysical parameters and temperature levelling effectiveness using a basic simulation model. However, in order to develop heat control systems for real electronic components, accurate estimations are needed [14]. Consequently, it is required to build a model for modelling that takes into account the PCM's thermophysical characteristics' temperature dependency. Several more variables affect the component PCMs' ability to level the temperatures in practical heating and cooling systems. The research used the assumption that the heating would be continuous, while real semiconductors undergo periodic cooling or heating [15]. As a result, a PCM's ability to level out at a given temperature is likewise impacted by the hysteresis of its phase change temperatures. For the phase change, PCMs that have elevated persistence need elevated temperature magnitudes. The climate-lowering performance is decreased by a discrepancy between the electronics chip's temperature magnitude and the PCM transition temperature sensitivity. Furthermore, due to space restrictions, the influence of Lv on temperature-levelling performance rises whenever a PCM with an outline smaller than wopt is connected. As a result, substances are chosen for actual components based on the intended device's physical restrictions and temperature-fluctuation interval.



**Figure 2**. Comparison of temperature of heat based on time

# Conclusion

To examine the temperature-levelling capabilities between two solid PCMs, VO2 and NiTi metals, heat models were run. We used the observed thermophysical characteristics for these PCMs to compute the amounts of optimal width (wopt) and maximal efficient energy ability, which are the functioning variables for PCMs installed on thin smart gadgets, depending on the manufactured PCM utilising heat models. The experimental verification of the simulation framework yielded excellent agreement between the simulated and experimental results. According to the model's findings, wopt and Eeff are reduced when an electronic chip's generated heat intensity (q) is increased. Consequently, when every PCM is installed in a device with intelligence, the variations in Eeff correspond to the variations in efficiency. The long life and expense of NiTi and VO2 as PCMs restrict their practical use. Due to their intricate manufacturing and limited payments, VO2 powder and nickel titanium alloy are costly materials. Additionally, it is yet unknown how long-lasting VO2 and nickel-tit are as PCMs that are It is thus essential to assess these PCMs' endurance in environments that are comparable to those that occur in real-life situations.

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